

Electronic Patent Application Fee Transmittal

Application Number:	10596387
Filing Date:	13-Apr-2007
Title of Invention:	EPOXY RESIN MOLDING MATERIAL FOR SEALING AND ELECTRONIC COMPONENT
First Named Inventor/Applicant Name:	Kazuyoshi Tendou
Filer:	Joerg-Uwe V. Szipl/Janice Rosier
Attorney Docket Number:	MIYOSH0006

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1510	1510
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Printed copy of patent - no color	8001	10	3	30
Total in USD (\$)				1840